

Appl. No. 10/008,337
Amendment and/or Response
Reply to Office action of 30 June 2003

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Amendments to the Claims:

A listing of the entire set of pending claims (including amendments to the claims, if any) is submitted herewith per 37 CFR 1.121. This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

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1. (Withdrawn) A method of fabricating an electronic device comprising:
forming a predetermined pattern of weakened regions in a layer of rigid material which define contiguous portions of the rigid layer;
providing electronic components on the rigid layer; and
forming flexible connectors which extend between components on different portions.
 2. (Withdrawn) The method of claim 1 including the step of dividing the rigid layer along the weakened regions.
 3. (Withdrawn) The method of claim 1 including the step of mounting the rigid layer over a flexible substrate.
 4. (Withdrawn) The method of claim 1 wherein the connectors are formed by electroplating metal onto the rigid layer.
 5. (Withdrawn) The method of claim 4 wherein a seed layer is deposited prior to electroplating the metal connectors.
 6. (Withdrawn) The method of claim 4 wherein areas of photoresist are defined over the rigid layer prior to electroplating the metal, such that portions of the connectors form bridges over the photoresist, and the photoresist is subsequently removed.

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7. (Withdrawn) A method of fabricating an electronic device comprising:
providing electronic components on a rigid layer;
forming flexible connectors which extend between components on different
contiguous portions of the rigid layer; and
dividing the rigid layer into the contiguous portions.
8. (Withdrawn) The method of claim 7 including the step of mounting the rigid layer over a
flexible substrate.
9. (Withdrawn) The method of claim 7 wherein the connectors are formed by electroplating
metal onto the rigid layer.
10. (Withdrawn) The method of claim 9 wherein a seed layer is deposited prior to
electroplating the metal connectors.
11. (Withdrawn) The method of claim 9 wherein areas of photoresist are defined over the
rigid layer prior to electroplating the metal, such that portions of the connectors form bridges
over the photoresist, and the photoresist is subsequently removed.
12. (Currently amended) An electronic device comprising a layer of rigid material having
electronic components mounted directly thereon, contiguous portions of the rigid layer being
defined by weakened regions of the rigid layer, and flexible connectors extending between
components on different portions.
13. (Previously presented) The device of claim 12 wherein the weakened regions comprise
grooves in one or both faces of the rigid layer.

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14. (Previously presented) The device of claim 12 wherein the rigid layer is mounted over a flexible substrate.
15. (Previously presented) The device of claim 12 wherein the connectors comprise electroplated metal.
16. (Previously presented) The device of claim 12 wherein the connectors comprise a bridge-like portion.
17. (Currently amended) An electronic device comprising a layer of rigid material having electronic components mounted directly thereon, and flexible connectors extending between components on different contiguous portions of the rigid layer, the rigid layer being divided into the contiguous portions such that the device is flexible.
18. (Previously presented) The device of claim 17 wherein the rigid layer has been divided into the contiguous portions along weakened regions of the rigid layer.
19. (Previously presented) The device of claim 18 wherein the weakened regions comprise grooves in one or both faces of the rigid layer.
20. (Previously presented) The device of claim 17 wherein the rigid layer is mounted over a flexible substrate.
21. (Previously presented) The device of claim 17 wherein the connectors comprise electroplated metal.
22. (Previously presented) The device of claim 17 wherein the connectors comprise a bridge-like portion.

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B' 23. (Currently amended) An article having an electronic device mounted thereon, the electronic device comprising a layer of rigid material having electronic components mounted directly thereon, contiguous portions of the rigid layer being defined by weakened regions of the rigid layer, and flexible connectors extending between components on different portions.

24. (Currently amended) An article having an electronic device mounted thereon, the electronic device comprising a layer of rigid material having electronic components mounted directly thereon, and flexible connectors extending between components on different contiguous portions of the rigid layer, the rigid layer being divided into the contiguous portions such that the device is flexible.
